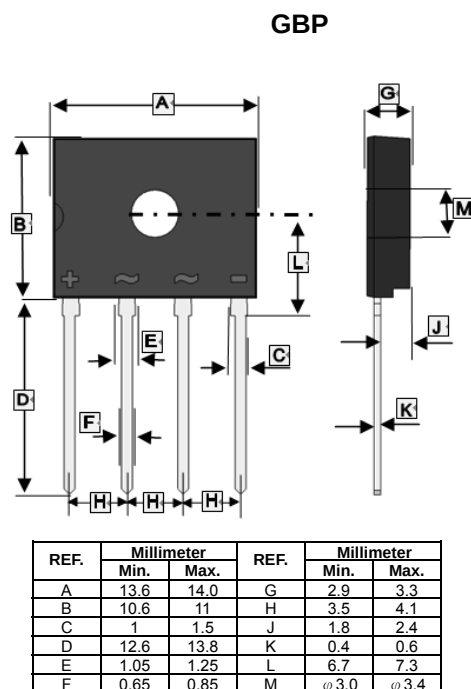


RoHS Compliant Product

FEATURES

- Ideal for printed circuit board
- Low forward voltage drop, high current capability
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- These are Halogen & Pb Free components
- This series is UL recognized under Component Index, file number E255340



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, de-rate current by 20%.)

Parameter		Symbol	Part Number				Unit
			S2GBP20-C	S2GBP40-C	S2GBP60-C	S2GBP80-C	
Maximum Recurrent Peak Reverse Voltage		V_{RRM}	200	400	600	800	V
Average Rectified Output Current @60HZ sine wave, R-load	$T_C=140^{\circ}\text{C}$ (with heat sink)	I_O	2				A
	$T_A=29^{\circ}\text{C}$ (without heat sink)		1.2				
Peak Forward Surge Current @ 60Hz sine wave, 1 cycle, $T_J=25^{\circ}\text{C}$		I_{FSM}	60				A
Maximum Peak Forward Voltage ³		V_{FM}	1.05				V
Peak Reverse Current ²		I_{RRM}	10				μA
I^2t Rating for Fusing @ $3\text{ms}\leq t<8.3\text{ms}$, $T_J=25^{\circ}\text{C}$,Rating of per diode		I^2t	15				A^2s
Mounting Torque @ Recommend torque:5kg·cm		TOR	8				Kg · cm
Dielectric Strength ¹		Vdis	2				kV
Typical Thermal Resistance (with heat sink)		$R_{\theta JC}$	1.5				$^{\circ}\text{C/W}$
Typical Thermal Resistance(without heat sink)		$R_{\theta JA}$	55				$^{\circ}\text{C/W}$
Typical Thermal Resistance(without heat sink)		$R_{\theta JL}$	15				$^{\circ}\text{C/W}$
Operating and Storage temperature range		T_J, T_{STG}	150, -55~150				$^{\circ}\text{C}$

Notes :

1. Terminals to case · AC 1 minute
2. $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode.
3. $I_{FM}=1\text{A}$, Pulse measurement, Rating of per diode

RATINGS AND CHARACTERISTIC CURVES

